



## 18V N-Channel Trench Power MOSFET

### General Description

The SJM18N035 uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a wide variety of applications.

### Features

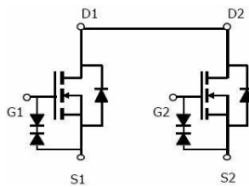
- Low Gate Charge
- High Power and current handling capability
- Lead free product is acquired
- ESD Rating: HBM 2KV

### Application

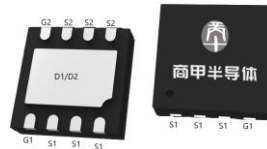
- Load Switch

### Key Performance Parameters

Parameter	Value	Unit
$V_{DS}$	18	V
$R_{DS(ON\_TYP)}$	3	m $\Omega$
$I_D$	58	A
$Q_G$	36	nC



Schematic Diagram



DFN3X3-8L top&bottom view



### Package Marking and Ordering Information

Device/Ordering Code	Marking	Package	Reel Size	Tape width	Quantity
SJM18N035	SJM18N035	DFN3X3-8L	\	\	\

Table 1. Absolute Maximum Ratings ( $T_C=25^{\circ}\text{C}$  unless otherwise noted)

Symbol	Parameter	Limit	Unit
$V_{DS}$	Drain-Source Voltage ( $V_{GS}=0\text{V}$ )	18	V
$V_{GS}$	Gate-Source Voltage ( $V_{DS}=0\text{V}$ )	$\pm 10$	V
$I_D$	Drain Current-Continuous( $T_C=25^{\circ}\text{C}$ )	58	A
	Drain Current-Continuous( $T_C=100^{\circ}\text{C}$ )	36	A
$I_{DM}$ (pulse)	Drain Current-Continuous@ Current-Pulsed (Note 1)	232	A
$P_D$	Maximum Power Dissipation( $T_C=25^{\circ}\text{C}$ )	22	W
	Maximum Power Dissipation( $T_C=100^{\circ}\text{C}$ )	8.7	W
$E_{AS}$	Avalanche energy (Note 2)	110	mJ
$T_J, T_{STG}$	Operating Junction and Storage Temperature Range	-55 To 150	$^{\circ}\text{C}$

Table 2. Thermal Characteristic

Symbol	Parameter	Typ	Max	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		5.7	$^{\circ}\text{C/W}$



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**Table 3. Electrical Characteristics ( $T_J=25^{\circ}\text{C}$  unless otherwise noted)**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
On/Off States						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	18			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =18V, V <sub>GS</sub> =0V T <sub>J</sub> =25℃			1	μA
		V <sub>DS</sub> =18V, V <sub>GS</sub> =0V T <sub>J</sub> =125℃			100	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>GS</sub> =±10V, V <sub>DS</sub> =0V			±10	uA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	0.5		1	V
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> =5V, I <sub>D</sub> =5A		13.6		S
R <sub>DS(ON)</sub>	Drain-Source On-State Resistance	V <sub>GS</sub> =4.5V, I <sub>D</sub> =5A T <sub>J</sub> =25℃		3	3.9	mΩ
R <sub>DS(ON)</sub>	Drain-Source On-State Resistance	V <sub>GS</sub> =2.5V, I <sub>D</sub> =4A T <sub>J</sub> =25℃		3.7	4.9	mΩ
Dynamic Characteristics						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =9V,V <sub>GS</sub> =0V, f=1.0KHz		2727		pF
C <sub>oss</sub>	Output Capacitance			332		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			306		pF
Switching Parameters						
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>GS</sub> =4.5V, V <sub>DS</sub> =9V, R <sub>L</sub> =1.8Ω, R <sub>GEN</sub> =3Ω		11		nS
t <sub>r</sub>	Turn-on Rise Time			34		nS
t <sub>d(off)</sub>	Turn-Off Delay Time			72		nS
t <sub>f</sub>	Turn-Off Fall Time			92		nS
Q <sub>g</sub>	Total Gate Charge	V <sub>GS</sub> =4.5V, V <sub>DS</sub> =9V, I <sub>D</sub> =5A		36		nC
Q <sub>gs</sub>	Gate-Source Charge			6		nC
Q <sub>gd</sub>	Gate-Drain Charge			10		nC
Source-Drain Diode Characteristics						
I <sub>SD</sub>	Source-Drain Current (Body Diode)				58	A
V <sub>SD</sub>	Forward on Voltage <sup>(Note 3)</sup>	V <sub>GS</sub> =0V, I <sub>S</sub> =5A			1.2	V

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature.

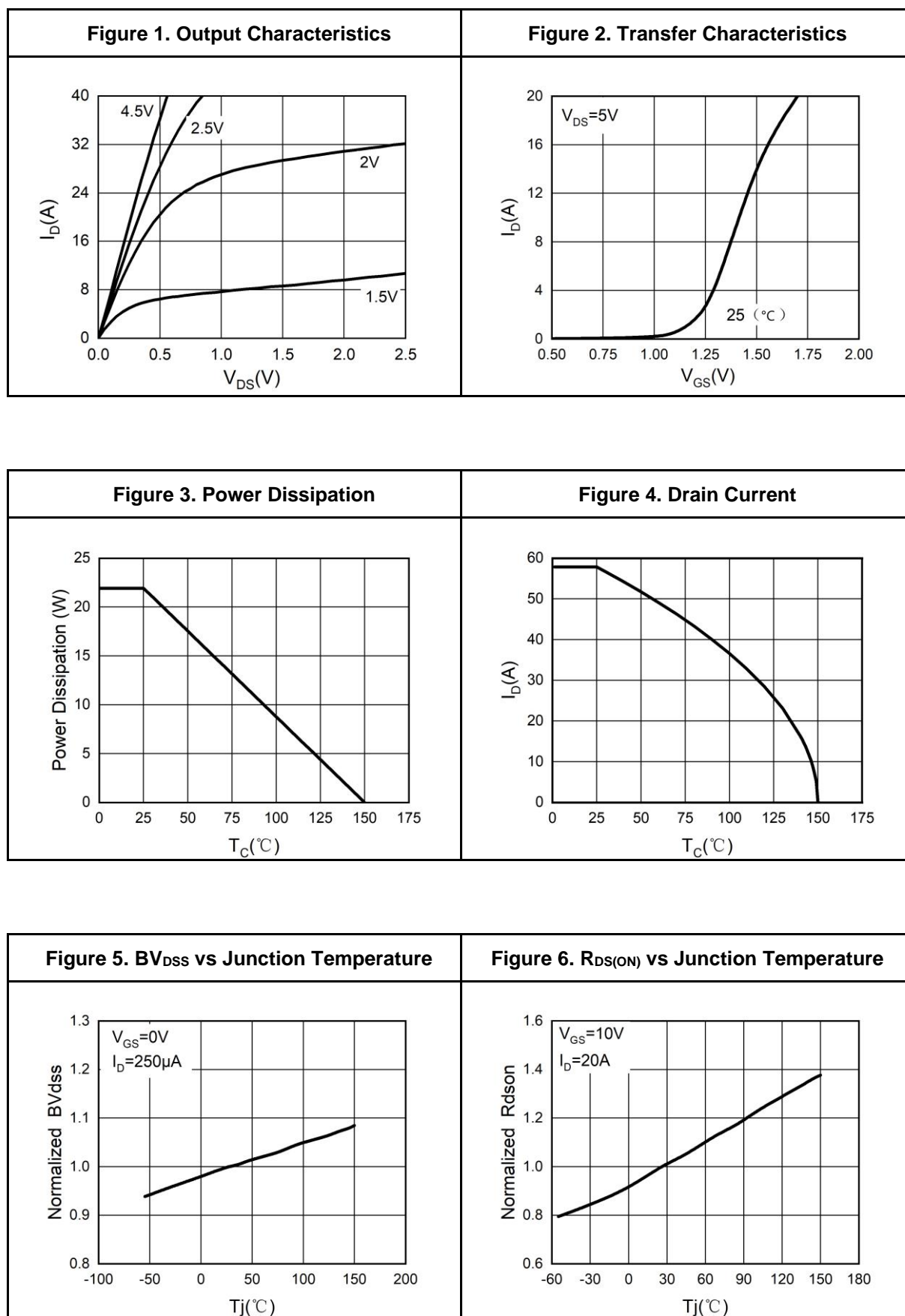
Notes 2.EAS condition:  $T_J=25^{\circ}\text{C}, V_{DD}=10V, V_G=10V, R_g=25\Omega, L=0.5mH$ .

Notes 3.Repetitive Rating: Pulse width limited by maximum junction temperature.



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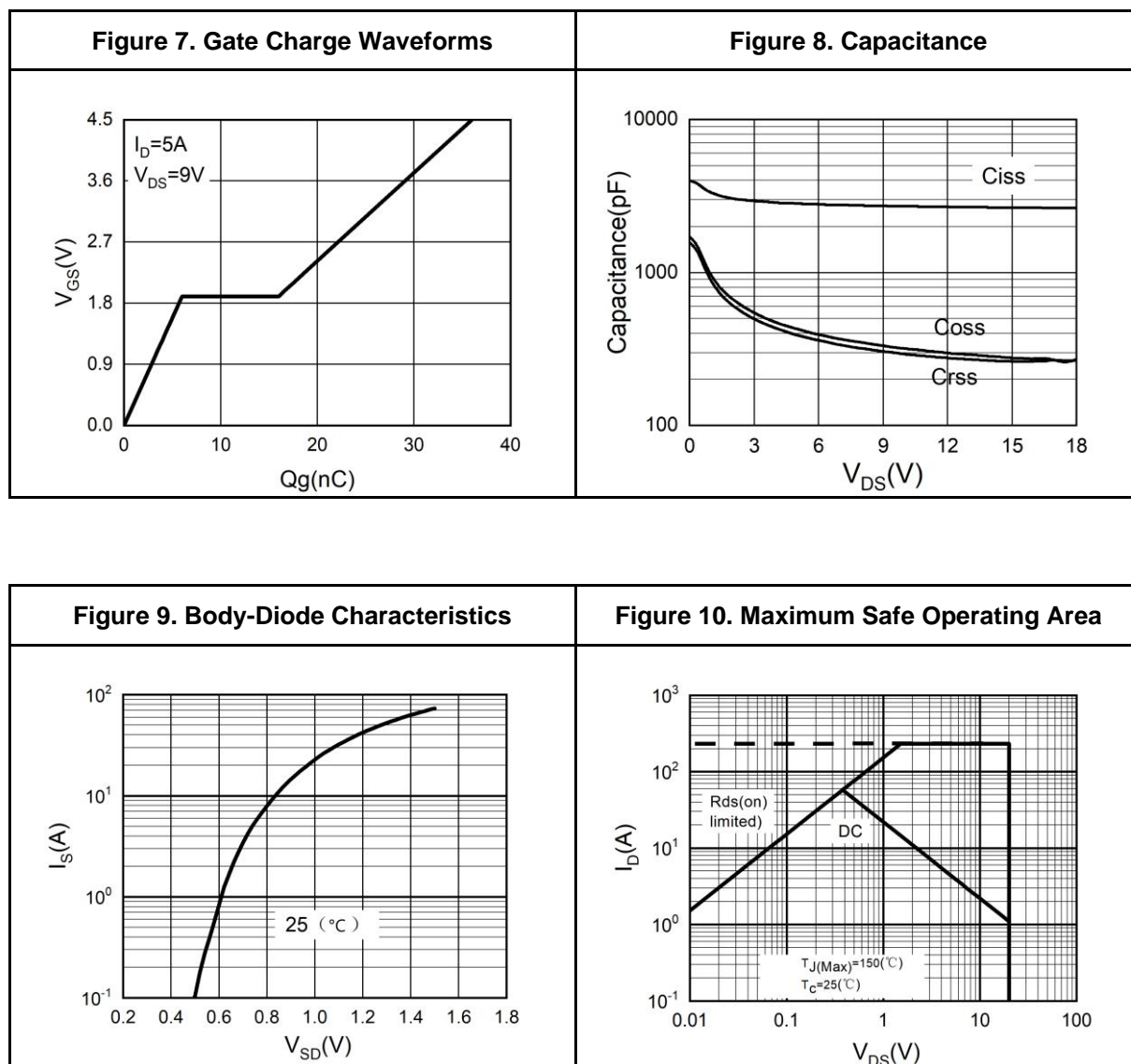
### Typical Electrical And Thermal Characteristics (Curves)





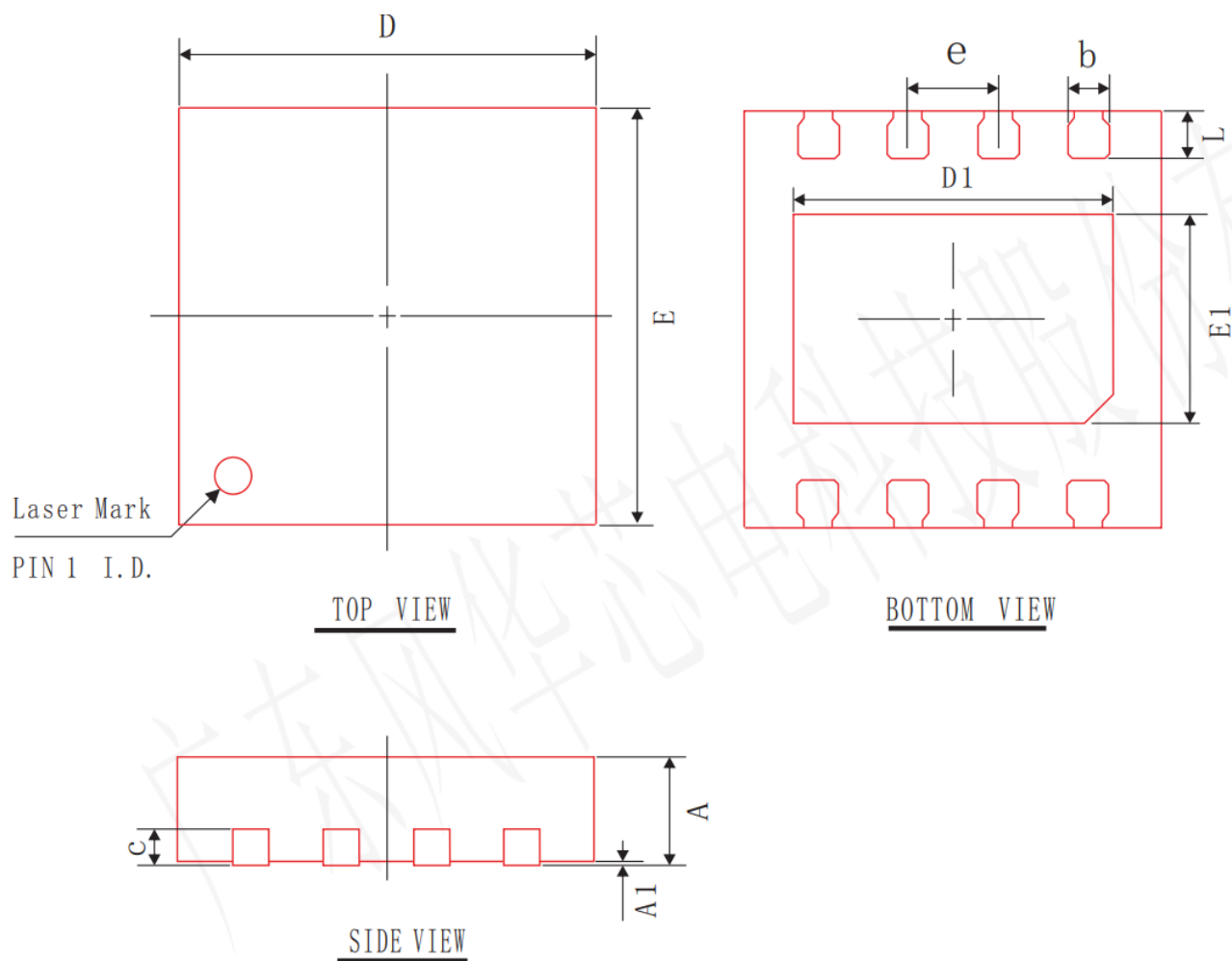
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### Typical Electrical And Thermal Characteristics (Curves)





## DFN3X3-8L Package Information



COMMON DIMENSIONS  
(UNITS OF MEASURE=mm)

SYMBOL	MIN	NOM	MAX
A	0.70	0.75	0.80
A1	0.00	0.02	0.05
b	0.25	0.30	0.35
D	2.95	3.00	3.07
E	2.95	3.00	3.07
D1	2.25	2.30	2.35
E1	1.40	1.50	1.60
L	0.25	0.35	0.45
c	0.203 REF		
e	0.65 BSC		

其它厚度尺寸如下

A	0.55	0.60	0.65
A	0.50	0.55	0.60



## Attention

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